

**Short Oral Presentation**

**Area 12:**

**PS-12**

**11:35-12:13 Meeting Room 1**

Session Chair: S. Ohya (Univ. of Tokyo)

H. Shimizu (Tokyo Univ. of Agri. & Tech.)

**10: Organic Materials Science, Device Physics,  
Applications and Printed Technologies**

**B-3: Fabrication and Characterization**

**9:30-11:15 Meeting Room 2**

Session Chair: T. Hayashi (NTT Basic Res. Labs.)

M. Nakamura (NAIST)

**9:30 B-3-01 (Invited)**

Fundamentals and Applications of Nano-molecular devices

<sup>o</sup>N. Clement<sup>1</sup>, <sup>1</sup>NTT Basic Res. Labs. (Japan)

**10:00 B-3-02**

Electron Injection on Metal/n-doped Polymer  
Semiconductor

<sup>o</sup>S. Sakiyama<sup>1</sup>, A. Yasukochi<sup>1</sup>, T. Iwashita<sup>1</sup>, K. Fujita<sup>1</sup>,  
<sup>1</sup>Kyushu Univ. (Japan)

**10:15 B-3-03**

Precipitation of thin film organic single crystals by a novel  
crystal growth method using electrospray and ionic liquid  
layer

<sup>o</sup>H. Ueda<sup>1</sup>, K. Takeuchi<sup>1</sup>, A. Kikuchi<sup>1,2</sup>, <sup>1</sup>Sophia Univ.  
(Japan), <sup>2</sup>Sophia Nanotechnology Research Center  
(Japan)

**10:30 B-3-04**

Theoretical Studies of  $\pi$ -Conjugate Molecules Embedded  
in hexagonal boron nitride

W. Xie<sup>1</sup>, T. Tamura<sup>1</sup>, T. Yanase<sup>1</sup>, T. Nagahama<sup>1</sup>, <sup>o</sup>T.  
Shimada<sup>1</sup>, <sup>1</sup>Hokkaido Univ. (Japan)

**Thursday, September 21**

**10:45 B-3-05**

A Design-analysis Flow Considering Mechanical Stability of Metal Masks for Organic CMOS Circuits

<sup>o</sup>M. Shintani<sup>1</sup>, K. Kuribara<sup>2</sup>, Y. Ogasahara<sup>2</sup>, M. Hiromoto<sup>1</sup>, T. Sato<sup>1</sup>, <sup>1</sup>Kyoto Univ. (Japan), <sup>2</sup>AIST (Japan)

**11:00 B-3-06**

Dimer Formation of Pentacene by Heated Tungsten

<sup>o</sup>A. Heya<sup>1</sup>, N. Matsuo<sup>1</sup>, <sup>1</sup>Univ. of Hyogo (Japan)

**11:15-11:35 Coffee Break**

**Short Oral Presentation**

**Area 10:**

**PS-10**

**11:35-11:55 Meeting Room 2**

Session Chair: T. Shimada (Hokkaido Univ.)

H. Endoh (NEC Corp.)

**11:55-14:00 Lunch**

**Luncheon Seminar**

**12:45-13:45**

EAG Nano Science Corporation (Hagi Conference Room)

Springer Nature (Tachibana Conference Room)

**Joint Session (Area 7&10)**

**B-4: Nano and Molecular Photonics**

**14:00-15:00 Meeting Room 2**

Session Chair: N. Nishiyama (Tokyo Tech)

T. Shimada (Hokkaido Univ.)

**14:00 B-4-01 (Invited)**

The Excitonics in Photonic Colloidal Nanostructures and Devices

H. Lee<sup>1</sup>, Y. Kim<sup>1</sup>, <sup>o</sup>S. Lee<sup>1</sup>, <sup>1</sup>Seoul National Univ. (Korea)

**14:30 B-4-02**

Optical Waveguides with Memory Effect Using Photochromic Material for Neural Network

<sup>o</sup>K. Tanimoto<sup>1</sup>, Y. Amemiya<sup>1</sup>, S. Yokoyama<sup>1</sup>, <sup>1</sup>Hiroshima

Thursday, September 21

Univ. (Japan)

**14:45 B-4-03**

Electroluminescence Color Tuning between Green and Red in MOS Devices Fabricated by Spin-coating of (Tb + Eu) Organic Compounds on Si

*T. Matsuda<sup>1</sup>, °F. Hattori<sup>1</sup>, H. Iwata<sup>1</sup>, T. Ohzone<sup>2</sup>, <sup>1</sup>Toyama Prefectural Univ. (Japan), <sup>2</sup>Dawn Enterprise Co., Ltd. (Japan)*

**15: Photovoltaic Materials and Devices**

**C-3: III-V Photovoltaics**

**9:30-10:30 Meeting Room 3**

Session Chair: H. Suzuki (Univ. of Miyazaki)

T. Hoshii (Tokyo Tech)

**9:30 C-3-01 (Invited)**

Next-generation High Efficiency and Low Cost GaAs/Si Multijunction Solar Cells with Smart Stack Technology

*°K. Makita<sup>1</sup>, H. Mizuno<sup>1</sup>, R. Oshima<sup>1</sup>, T. Tayagaki<sup>1</sup>, M. Baba<sup>2</sup>, N. Yamada<sup>2</sup>, H. Takato<sup>1</sup>, T. Sugaya<sup>1</sup>, <sup>1</sup>AIST (Japan), <sup>2</sup>Nagaoka Univ. of Tech. (Japan)*

**10:00 C-3-02**

Improvement in Effective Optical Absorbency for the Bottom Cells of Mechanical Stacked Multi-Junction Solar Cells

*°M. Hasumi<sup>1</sup>, Y. Ogawa<sup>1</sup>, K. Oshinari<sup>1</sup>, T. Sameshima<sup>1</sup>, <sup>1</sup>Tokyo Univ. of Agri. & Tech. (Japan)*

**10:15 C-3-03**

Investigation of the Open-Circuit Voltage in the Wide-Bandgap InGaP-based InP Quantum Dot Solar Cells

*°T. Aihara<sup>1</sup>, T. Tayagaki<sup>1</sup>, Y. Nagato<sup>2</sup>, Y. Okano<sup>2</sup>, T. Sugaya<sup>1</sup>, <sup>1</sup>AIST (Japan), <sup>2</sup>Tokyo City Univ. (Japan)*

**10:30-11:35**

**Coffee Break**

**Short Oral Presentation**

**Area 15:**

**PS-15**

**11:35-11:57 Meeting Room 3**

Session Chair: M. Ikegami (Toin Univ. of Yokohama)  
K. Ohdaira (JAIST)

**Joint Session (Area 4&5&9&12)**

**D-3: Non von Neumann Computing II**

**9:30-11:10 Hagi Conference Room**

Session Chair: T. Sakamoto (NEC Corp.)  
I. Akita (Toyohashi Tech)

**9:30 D-3-01 (Invited)**

“More-than-Neumann” and “Beyond-Neumann”  
Architectures

°*T. Asai<sup>1</sup>, <sup>1</sup>Hokkaido Univ. (Japan)*

**10:00 D-3-02**

An Energy Efficient and High Speed Architecture for  
Convolution Computing Based on Binary RRAMs

°*C. Liu<sup>1</sup>, R. Han<sup>1</sup>, Z. Zhou<sup>1</sup>, P. Huang<sup>1</sup>, L. Liu<sup>1</sup>, X. Liu<sup>1</sup>, J. Kang<sup>1</sup>, <sup>1</sup>Peking Univ. (China)*

**10:20 D-3-03**

Characteristics of Crystalline Oxide Semiconductor-based  
Single Transistor Multiplier for Analog Neural Network

°*T. Aoki<sup>1</sup>, S. Harada<sup>1</sup>, Y. Okamoto<sup>1</sup>, T. Nakagawa<sup>1</sup>, H. Inoue<sup>1</sup>, T. Ikeda<sup>1</sup>, Y. Kurokawa<sup>1</sup>, Y. Shima<sup>1</sup>, M. Jincho<sup>1</sup>, M. Ikeda<sup>2</sup>, S. Yamazaki<sup>1</sup>, <sup>1</sup>Semiconductor Energy Lab. Co., Ltd. (Japan), <sup>2</sup>Univ. of Tokyo (Japan)*

**10:40 D-3-04**

A Study of Validation of an Evaluation Model of Accurate  
Thermal Stability Factor for MTJs Using Its Thermal  
Dependency

°*T. Saito<sup>1,2,3</sup>, T. Endoh<sup>1,2,3</sup>, <sup>1</sup>Tohoku Univ. (Japan), <sup>2</sup>ACCEL, JST (Japan), <sup>3</sup>OPERA, JST (Japan)*

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**10:55 D-3-05**

Design of an MTJ-Oriented Nonvolatile Lookup Table  
Circuit with Write-Operation Minimizing

*°D. Suzuki<sup>1</sup>, T. Hanyu<sup>1</sup>, <sup>1</sup>Tohoku Univ. (Japan)*

**11:10-11:35 Coffee Break**

**Short Oral Presentation**

**Area 4:**

**PS-4**

**11:35-12:05 Hagi Conference Room**

Session Chair: T. Sakamoto (NEC Corp.)

**Short Oral Presentation**

**Area 5:**

**PS-5**

**12:05-12:25 Hagi Conference Room**

Session Chair: T. Yoshida (Hiroshima Univ.)

**12:25-14:00 Lunch**

**Luncheon Seminar**

**12:45-13:45**

EAG Nano Science Corporation (Hagi Conference Room)

Springer Nature (Tachibana Conference Room)

**Joint Session (Area 4&5&9&12)**

**D-4: Non von Neumann Computing III**

**14:00-15:15 Hagi Conference Room**

Session Chair: J. Nitta (Tohoku Univ.)

Y. Nishi (Toshiba Corp.)

**14:00 D-4-01 (Invited)**

Neuromorphic computing with spintronic nanoscale  
oscillators

*°J. Torrejon<sup>1</sup>, M. Riou<sup>1</sup>, F. A. Araujo<sup>1</sup>, S. Tsunegi<sup>2</sup>, G.*

*Khalsa<sup>3</sup>, D. Querlioz<sup>4</sup>, P. Bortolotti<sup>1</sup>, V. Cros<sup>1</sup>, A.*

*Fukushima<sup>2</sup>, H. Kubota<sup>2</sup>, S. Yuasa<sup>2</sup>, M. D. Stiles<sup>3</sup>, J.*

*Grollier<sup>1</sup>, <sup>1</sup>Unite Mixte de Physique, CNRS/Thales*

## Thursday, September 21

(France), <sup>2</sup>AIST (Japan), <sup>3</sup>National Inst. of Standards and Tech. (USA), <sup>4</sup>Centre de Nanosciences et de Nanotechnologies, CNRS, Université Paris-Saclay (France)

### 14:30 D-4-02

Neuromorphic Transistor Achieved by Redox Reaction of WO<sub>3</sub> Thin Film

°M. Jayabalan<sup>1,2</sup>, K. Kawamura<sup>1,3</sup>, M. Takayanagi<sup>1,3</sup>, T. Tsuchiya<sup>1</sup>, T. Higuchi<sup>3</sup>, R. Jayavel<sup>2</sup>, K. Terabe<sup>1</sup>, <sup>1</sup>NIMS (Japan), <sup>2</sup>Anna Univ. (India), <sup>3</sup>Tokyo Univ. of Sci. (Japan)

### 14:45 D-4-03

Artificial neuron operations and spike-timing-dependent plasticity (STDP) using memristive devices for brain-inspired computing

°T. Marukame<sup>1</sup>, R. Ichihara<sup>1</sup>, M. Mori<sup>1</sup>, Y. Nishi<sup>1</sup>, S. Yasuda<sup>1</sup>, T. Tanamoto<sup>1</sup>, Y. Mitani<sup>1</sup>, <sup>1</sup>Toshiba Corp. (Japan)

### 15:00 D-4-04

Application of VO<sub>2</sub> metal-insulator transition to capacitorless neuron circuits

°T. Yajima<sup>1</sup>, T. Nishimura<sup>1</sup>, A. Toriumi<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan)

## 03: CMOS Devices / Device Physics

### E-3: TFETs

#### 9:30-11:00 Tachibana Conference Room

Session Chair: T. Matsukawa (AIST)

S. Cho (Gachon Univ.)

#### 9:30 E-3-01 (Invited)

Performance Evaluation of III-V Nanowire Broken-Gap TFETs Including Electron-Phonon Scattering Using an Atomistic Mode Space NEGF Technique Enabling Million Atoms NW Simulations.

°A. Afzalian<sup>1</sup>, T. Vasen<sup>1</sup>, P. Ramvall<sup>1</sup>, D. Lemus<sup>2</sup>, T. Kubis<sup>2</sup>, M. Passlack<sup>1</sup>, T. -M. Shen<sup>3</sup>, J. Wu<sup>3</sup>, <sup>1</sup>TSMC, Leuven (Belgium), <sup>2</sup>Purdue Univ. (USA), <sup>3</sup>TSMC, Hsinchu (Taiwan)

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### 10:00 E-3-02

Investigation of TFETs with Vertical Tunneling Path for Low Average Subthreshold Swing

°S. Glass<sup>1</sup>, N. von den Driesch<sup>1</sup>, S. Strangio<sup>2</sup>, C. Schulte-Braucks<sup>1</sup>, T. Rieger<sup>1</sup>, D. Buca<sup>1</sup>, S. Mantl<sup>1</sup>, Q. -T. Zhao<sup>1</sup>,  
<sup>1</sup>Forschungszentrum Juelich (Germany), <sup>2</sup>Univ. of Udine (Italy)

### 10:20 E-3-03

Performance Improvement of Ge-source/Si-channel Hetero-Junction Tunneling FETs: Effects of Annealing Gas and Drain Doping Concentration

°T. -E. Bae<sup>1</sup>, Y. Wakabayashi<sup>1</sup>, R. Nakane<sup>1</sup>, M. Takenaka<sup>1</sup>, S. Takagi<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan)

### 10:40 E-3-04

Ge p-channel Tunneling FETs with Steep Phosphorus Profile Source Junctions

°R. Takaguchi<sup>1</sup>, R. Matsumura<sup>1</sup>, T. Katoh<sup>1</sup>, M. Takenaka<sup>1</sup>, S. Takagi<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan)

**11:00-11:35 Coffee Break**

**Short Oral Presentation**

**Area 3:**

**PS-3**

**11:35-12:07 Tachibana Conference Room**

Session Chair: T. Miyata (Toshiba Memory Corp.)

Y. Fukuzaki (Sony Semiconductor Solutions Corp.)

**12:07-14:00 Lunch**

**Luncheon Seminar**

**12:45-13:45**

EAG Nano Science Corporation (Hagi Conference Room)

Springer Nature (Tachibana Conference Room)

**03: CMOS Devices / Device Physics**

**E-4: Negative-Capacitance Transistors**

**14:00-15:00 Tachibana Conference Room**

Session Chair: M. Kobayashi (Univ. of Tokyo)  
P. Su (NCTU)

**14:00 E-4-01**

Design of Steep Slope Negative Capacitance FinFETs for Dense Integration: Matching of Channel and Ferroelectric Capacitances

*°H. Ota<sup>1</sup>, J. Hattori<sup>1</sup>, H. Asai<sup>1</sup>, T. Ikegami<sup>1</sup>, K. Fukuda<sup>1</sup>, S. Migita<sup>1</sup>, A. Toriumi<sup>2</sup>, <sup>1</sup>AIST (Japan), <sup>2</sup>Univ. of Tokyo (Japan)*

**14:20 E-4-02**

Investigation of Quantum-Induced VT Shift and Backgate-Modulated VT Properties for Ultra-Thin-Body InGaAs-OI/SOI Negative-Capacitance FETs

*°S. -E. Huang<sup>1</sup>, C. -L. Yu<sup>1</sup>, W. -X. You<sup>1</sup>, P. Su<sup>1</sup>, <sup>1</sup>National Chiao Tung Univ. (Taiwan)*

**14:40 E-4-03**

Fringing Field Effects in Ferroelectric Negative Capacitance Field-Effect Transistors

*°J. Hattori<sup>1</sup>, K. Fukuda<sup>1</sup>, T. Ikegami<sup>1</sup>, H. Ota<sup>1</sup>, S. Migita<sup>1</sup>, H. Asai<sup>1</sup>, A. Toriumi<sup>2</sup>, <sup>1</sup>AIST (Japan), <sup>2</sup>Univ. of Tokyo (Japan)*

**11: Sensors and Materials for Biology, Chemistry and Medicine**

**F-3: Biosensors & Materials**

**9:30-11:00 Meeting Room 4**

Session Chair: T. Tanaka (Tohoku Univ.)  
S. Machida (Hitachi, Ltd.)

**9:30 F-3-01 (Invited)**

Diamond Quantum Sensors for Biological Application

*°M. Hatano<sup>1</sup>, H. Ishiwata<sup>1</sup>, T. Iwasaki<sup>1</sup>, <sup>1</sup>Tokyo Tech (Japan)*



## Thursday, September 21

### 10:00 F-3-02

Multiple Channel Detection of Cellular Activities by Ion Sensitive Transistors

°S. Machida<sup>1</sup>, <sup>1</sup>Toyota Central R&D Labs. Inc. (Japan)

### 10:15 F-3-03

Development of the Micro-electrode Device for Electrical Diagnosis and Cure for Skin Function

°Y. Abe<sup>1</sup>, K. Nagamine<sup>1</sup>, M. Nakabayashi<sup>1</sup>, T. Yamauchi<sup>1</sup>, K. Yamasaki<sup>1</sup>, M. Nishizawa<sup>1</sup>, <sup>1</sup>Tohoku Univ. (Japan)

### 10:30 F-3-04

Ultra-sensitive biosensor with capacitive coupling-gate InGaZnO-based FET

°K. Ito<sup>1</sup>, K. Nishimura<sup>1</sup>, K. Ikeda<sup>2</sup>, K. Matsuzawa<sup>2</sup>, T. Tezuka<sup>2</sup>, T. Sakata<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan), <sup>2</sup>Toshiba Corp. (Japan)

### 10:45 F-3-05 (Late News)

Surface Modification with Aryldiazonium Salt Chemistry of Extended-Au Gate Field-Effect Transistor for Ultra-Sensitive Detection of Low-Molecular-Weight Biomarker

°S. Nishitani<sup>1</sup>, T. Sakata<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan)

**11:00-11:35 Coffee Break**

### Short Oral Presentation

#### Area 11:

#### PS-11

#### 11:35-12:01 Meeting Room 4

Session Chair: T. Tokuda (NAIST)

T. Sakata (Univ. of Tokyo)

**12:01-14:00 Lunch**

#### Luncheon Seminar

#### 12:45-13:45

EAG Nano Science Corporation (Hagi Conference Room)  
Springer Nature (Tachibana Conference Room)

**11: Sensors and Materials for Biology, Chemistry and Medicine**

**F-4: Bio-MEMS**

**14:00-15:15 Meeting Room 4**

Session Chair: H. Tanaka (Panasonic Corp.)  
T. Tokuda (NAIST)

**14:00 F-4-01 (Invited)**

Integrated photonics for miniature flow cytometry

<sup>o</sup>N. Verellen<sup>1</sup>, D. Vercruyse<sup>1</sup>, V. Rochus<sup>1</sup>, B. D. Bois<sup>1</sup>, A. Dusa<sup>1</sup>, S. Kerman<sup>1</sup>, M. Mahmud-Ul-Hasan<sup>1</sup>, P. V. Dorpe<sup>1</sup>, X. Rottenberg<sup>1</sup>, L. Lagae<sup>1</sup>, <sup>1</sup>IMEC (Belgium)

**14:30 F-4-02**

A micro through-hole chip device for analyzing plasma-irradiation effects on proliferation of cells cultured in liquid media

Y. Nakanishi<sup>1</sup>, M. Kobayashi<sup>2</sup>, M. Sasaki<sup>1</sup>, <sup>o</sup>S. Kumagai<sup>1</sup>, <sup>1</sup>Toyota Tech. Inst. (Japan), <sup>2</sup>NAIST (Japan)

**14:45 F-4-03**

Label Free Detection of Prostate Specific Antigen Using Photonic Crystal Nanocavity Resonator

<sup>o</sup>A. K. Sana<sup>1</sup>, Y. Amemiya<sup>1</sup>, T. Ikeda<sup>1</sup>, A. Kuroda<sup>1</sup>, S. Yokoyama<sup>1</sup>, <sup>1</sup>Hiroshima Univ. (Japan)

**15:00 F-4-04**

Frequency-response curves of micropatterned hippocampal neurons: Effect of cell morphology on membrane impedance

<sup>o</sup>R. Matsumura<sup>1</sup>, H. Yamamoto<sup>1</sup>, S. Katsurabayashi<sup>2</sup>, M. Niwano<sup>1</sup>, A. Hirano-Iwata<sup>1</sup>, <sup>1</sup>Tohoku Univ. (Japan), <sup>2</sup>Fukuoka Univ. (Japan)

**07: Photonic Devices and Related Technologies**

**G-3: Novel Photonic Devices**

**9:30-11:15 Meeting Room 5**

Session Chair: H. Isshiki (Univ. of Electro-Communications)  
N. Ozaki (Wakayama Univ.)

**9:30 G-3-01**

Deformable 1D Photonic Crystal Nanolasers for Planar Strain Identification

°*T. -W. Lu<sup>1</sup>, C. -C. Wu<sup>1</sup>, P. -T. Lee<sup>1</sup>, <sup>1</sup>National Chiao Tung Univ. (Taiwan)*

**9:45 G-3-02**

Sublattice Reversal in GaAs/Ge/GaAs (113)B

heterostructures and its application to THz emitting devices based on a coupled multilayer cavity

°*X. Lu<sup>1</sup>, Y. Minami<sup>1</sup>, N. Kumagai<sup>2</sup>, T. Kitada<sup>1</sup>, <sup>1</sup>Tokushima Univ. (Japan), <sup>2</sup>AIST (Japan)*

**10:00 G-3-03**

CMOS Single-Photon Avalanche Diodes for Light Detection and Ranging in Strong Background Illumination

°*W. -S. Huang<sup>1</sup>, T. -H. Liu<sup>1</sup>, D. -R. Wu<sup>1</sup>, C. -M. Tsai<sup>1</sup>, S. -D. Lin<sup>1</sup>, <sup>1</sup>National Chiao Tung Univ. (Taiwan)*

**10:15 G-3-04**

Estimation of the Conversion Properties of Trench-Structured Silicon X-ray Photodiodes by the Side X-ray Irradiation Method

°*T. Ariyoshi<sup>1</sup>, Y. Takane<sup>1</sup>, J. Iwasa<sup>1</sup>, K. Sakamoto<sup>1</sup>, A. Baba<sup>1</sup>, Y. Arima<sup>1</sup>, <sup>1</sup>Kyushu Inst. of Tech. (Japan)*

**10:30 G-3-05**

Compact Waveguide-Coupled Hybrid Plasmonic Nanotaper for Optical Trapping of Nanoparticles

°*Y. -C. Lin<sup>1</sup>, P. -T. Lee<sup>1</sup>, <sup>1</sup>National Chiao Tung Univ. (Taiwan)*

**10:45 G-3-06**

Population trapping through spectral hole burning in  $^{167}\text{Er}^{3+}:\text{Y}_2\text{SiO}_5$

*M. IJspeert<sup>1</sup>, G. Mariani<sup>1</sup>, °T. Tawara<sup>1,2</sup>, K. Shimizu<sup>1</sup>, H. Omi<sup>1,2</sup>, S. Adachi<sup>3</sup>, H. Gotoh<sup>1</sup>, <sup>1</sup>NTT Basic Res. Labs. (Japan), <sup>2</sup>NTT Nanophotonics Center (Japan), <sup>3</sup>Hokkaido Univ. (Japan)*

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**11:00 G-3-07 (Late News)**

Room-Temperature Two-Color Lasing by Current Injection into a GaAs/AlGaAs Coupled Multilayer Cavity Fabricated by Wafer Bonding

°T. Kitada<sup>1</sup>, X. Lu<sup>1</sup>, Y. Minami<sup>1</sup>, N. Kumagai<sup>2</sup>, K. Morita<sup>3</sup>,  
<sup>1</sup>Tokushima Univ. (Japan), <sup>2</sup>AIST (Japan), <sup>3</sup>Chiba Univ. (Japan)

**11:15-11:35 Coffee Break**

**Short Oral Presentation**

**Area 7:**

**PS-7**

**11:35-11:57 Meeting Room 5**

Session Chair: N. Nishiyama (Tokyo Tech)

**02: Interconnect Technologies, MEMS, and Reliability**

**H-3: Bump Interconnect**

**9:30-11:20 Meeting Room 6**

Session Chair: S. Ogawa (AIST)

J. M. Song (National Chung Hsing Univ.)

**9:30 H-3-01 (Invited)**

Effect of Metallization on the Microstructural Evolution of Microbump under Electric Current Stressing

C. -W. Chen<sup>1</sup>, °K. -L. Lin<sup>1</sup>, <sup>1</sup>National Cheng Kung Univ. (Taiwan)

**10:00 H-3-02**

Enhancement of Direct Cu Bonding via Pulsed Flash Light

°J. -M. Song<sup>1</sup>, S. -Y. Liang<sup>1</sup>, P. -H. Chiang<sup>1</sup>, S. -K. Huang<sup>2</sup>,  
Y. -T. Chiu<sup>2</sup>, D. Tarng<sup>2</sup>, C. -P. Hung<sup>2</sup>, <sup>1</sup>National Chung Hsing Univ. (Taiwan), <sup>2</sup>Advanced Semiconductor Engineering Group (Taiwan)

**10:20 H-3-03**

Low Temperature Cu to Cu Direct Bonding in Atmosphere Environment Using Pillar-Concave Structure in 3D Integration

## Thursday, September 21

°T. -C. Chou<sup>1</sup>, <sup>1</sup>National Chiao Tung Univ. (Taiwan)

### 10:40 H-3-04

Development of a technology platform using advanced die-first FOWLP for highly integrated flexible hybrid electronics

°T. Fukushima<sup>1,2</sup>, A. Alam<sup>1</sup>, A. Hanna<sup>1</sup>, S. C. Jangam<sup>1</sup>, A. Bajwa<sup>1</sup>, S. S. Iyer<sup>1</sup>, <sup>1</sup>UCLA (USA), <sup>2</sup>Tohoku Univ. (Japan)

### 11:00 H-3-05

N5 BEOL Process Options Patterning flows Comparing 193immersion to Hybrid EUV or Full EUV

°S. Lariviere<sup>1</sup>, B. Briggs<sup>1</sup>, C. Wilson<sup>1</sup>, D. Wan<sup>1</sup>, A. Mallik<sup>1</sup>, S. Decoster<sup>1</sup>, J. Bekaert<sup>1</sup>, V. Blanco<sup>1</sup>, M. Mao<sup>1</sup>, S. Paolillo<sup>1</sup>, B. K. Kotowska<sup>1</sup>, J. Versluijs<sup>1</sup>, J. Boemmels<sup>1</sup>, D. Trivkovic<sup>1</sup>, Z. Tokei<sup>1</sup>, G. Mcintyre<sup>1</sup>, D. Mocuta<sup>1</sup>, <sup>1</sup>IMEC (Belgium)

**11:20-11:35 Coffee Break**

## Short Oral Presentation

### Area 2:

#### PS-2

### 11:35-11:49 Meeting Room 6

Session Chair: M. B. Takeyama (Kitami Inst. of Tech.)

### Area 9:

#### PS-9

### 11:49-12:11 Meeting Room 6

Session Chair: K. Terabe (NIMS)

R. Moriya (Univ. of Tokyo)

**12:11-14:00 Lunch**

## 02: Interconnect Technologies, MEMS, and Reliability

### H-4: Bonding Technologies

### 14:00-15:35 Meeting Room 6

Session Chair: M. Kodera (Toshiba Electronic Devices & Storage Corp.)

M. Fujino (Univ. of Tokyo)

Thursday, September 21

**14:00 H-4-01**

Impacts of annealing on interfaces of Al foil/Si junctions by using surface activated bonding

°K. Furuna<sup>1</sup>, J. Liang<sup>1</sup>, M. Matsubara<sup>2</sup>, D. Marwan<sup>2</sup>, Y. Nishio<sup>2</sup>, N. Shigekawa<sup>1</sup>, <sup>1</sup>Osaka City Univ. (Japan), <sup>2</sup>Toyo Aluminium K.K. (Japan)

**14:20 H-4-02**

Fabrication of Mechanical Durable Glass Nanopillar with Bridged Structure

°H. Kuwae<sup>1</sup>, T. Sudo<sup>1</sup>, K. Takayama<sup>2</sup>, S. Shoji<sup>1</sup>, J. Mizuno<sup>1</sup>, <sup>1</sup>Waseda Univ. (Japan), <sup>2</sup>Asahi Glass Corp. (Japan)

**14:40 H-4-03**

Influence of atomic species of fast atom bombardment for surface activated bonding interface of germanium

°M. Fujino<sup>1</sup>, G. Kono<sup>1</sup>, T. Suga<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan)

**15:00 H-4-04**

Bonding and Debonding of Si/Glass based on SAB Method Combined with Hydrophilic Treatment

°K. Takeuchi<sup>1</sup>, Y. Matsumoto<sup>2</sup>, T. Suga<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan), <sup>2</sup>Lan Technical Service Co., Ltd. (Japan)

**15:20 H-4-05 (Late News)**

Au thin film wafer bonding after degas annealing for MEMS packaging

°T. Matsumae<sup>1</sup>, Y. Kurashima<sup>1</sup>, H. Takagi<sup>1</sup>, <sup>1</sup>AIST (Japan)

**13: Applications of Nanotubes, Nanowires, and Graphene and related 2D materials**

**J-3: 2D Materials and Devices II**

**9:30-11:15 Meeting Room 7**

Session Chair: K. Maehashi (Tokyo Univ. of Agri. & Tech.)  
T. Kato (Tohoku Univ.)

**9:30 J-3-01 (Invited)**

Novel Graphene Devices

Y. -C. Qiao<sup>1</sup>, H. Tian<sup>1</sup>, L. -Q. Tao<sup>1</sup>, N. -Q. Deng<sup>1</sup>, Y. -T. Li<sup>1</sup>, Y. -X. Li<sup>1</sup>, Y. Pang<sup>1</sup>, Y. Yang<sup>1</sup>, °T. -L. Ren<sup>1</sup>, <sup>1</sup>Tsinghua Univ.

(China)

**10:00 J-3-02**

Low-Resistance Contact to Single-Layer MoS<sub>2</sub> by Depositing Ultrathin High-k Dielectric with Remote N<sub>2</sub> Plasma Treatment as Tunneling Layer

°Q. Qian<sup>1</sup>, Z. Zhang<sup>1</sup>, M. Hua<sup>1</sup>, J. Wei<sup>1</sup>, J. Lei<sup>1</sup>, K. J. Chen<sup>1</sup>,  
<sup>1</sup>Hong Kong Univ. of Sci. and Tech. (Hong Kong)

**10:15 J-3-03**

Quantitative study of interfacial properties in monolayer MoS<sub>2</sub> FET

°N. Fang<sup>1</sup>, K. Nagashio<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan)

**10:30 J-3-04**

Conductance control by tunneling-barrier thickness optimizations in Fe/Al<sub>2</sub>O<sub>3</sub>/MoS<sub>2</sub> structure

°N. Hayakawa<sup>1</sup>, I. Muneta<sup>1</sup>, T. Ohashi<sup>1</sup>, K. Matsuura<sup>1</sup>, J. Shimizu<sup>1</sup>, K. Kakushima<sup>1</sup>, K. Tsustui<sup>1</sup>, H. Wakabayashi<sup>1</sup>,  
<sup>1</sup>Tokyo Tech (Japan)

**10:45 J-3-05**

Resonant Enhancement of Band-to-band Tunneling in In-plane MoS<sub>2</sub>/WS<sub>2</sub> Heterojunctions

°T. Kuroda<sup>1</sup>, N. Mori<sup>1</sup>, <sup>1</sup>Osaka Univ. (Japan)

**11:00 J-3-06**

Demonstration of p-type graphene barristor using a Schottky contact between graphene and p-type organic semiconductor

°K. Han<sup>1</sup>, Y. J. Kim<sup>1</sup>, S. Heo<sup>1</sup>, C. -H. Kim<sup>1</sup>, J. H. Kim<sup>1</sup>, S. -Y. Kim<sup>1</sup>, H. J. Hwang<sup>1</sup>, S. K. Lee<sup>1</sup>, H. J. Lee<sup>1</sup>, M. -H. Yoon<sup>1</sup>, B. H. Lee<sup>1</sup>, <sup>1</sup>Gwangju Inst. of Sci. and Tech. (Korea)

**11:15-11:35**

**Coffee Break**

Thursday, September 21

**Short Oral Presentation**

**Area 13:**

**PS-13**

**11:35-12:25 Meeting Room 7**

Session Chair: K. Nagashio (Univ. of Tokyo)

S. Hara (Hokkaido Univ.)

**12:25-14:00**

**Lunch**

**Luncheon Seminar**

**12:45-13:45**

EAG Nano Science Corporation (Hagi Conference Room)

Springer Nature (Tachibana Conference Room)

**13: Applications of Nanotubes, Nanowires, and Graphene and related 2D materials**

**J-4: Low-Dimensional Materials and Devices**

**14:00-15:15 Meeting Room 7**

Session Chair: H. Kageshima (Shimane Univ.)

T. Kawai (NEC Corp.)

**14:00 J-4-01**

Random Telegraph Noise in *h*-BN under Constant-Voltage Stress Test

<sup>o</sup>*Y. Hattori*<sup>1</sup>, *T. Taniguchi*<sup>2</sup>, *K. Watanabe*<sup>2</sup>, *K. Nagashio*<sup>1,3</sup>,  
<sup>1</sup>*Univ. of Tokyo (Japan)*, <sup>2</sup>*NIMS (Japan)*, <sup>3</sup>*PRESTO-JST (Japan)*

**14:15 J-4-02**

Electronic States of Silicene and Germanene on Amorphous Alumina

<sup>o</sup>*M. Araidai*<sup>1</sup>, *M. Kurosawa*<sup>1</sup>, *A. Ohta*<sup>1</sup>, *K. Shiraishi*<sup>1</sup>,  
<sup>1</sup>*Nagoya Univ. (Japan)*

**14:30 J-4-03**

Oxygen-Induced Structural Deterioration and Effective Encapsulation of Few-Layer 1T'-MoTe<sub>2</sub> Thin Film

*Z. Xie*<sup>1</sup>, *L. Yang*<sup>1</sup>, *H. Wu*<sup>1</sup>, *J. Li*<sup>1</sup>, *X. Lou*<sup>1</sup>, *R. Zhu*<sup>1</sup>, *H. Chang*<sup>1</sup>, <sup>o</sup>*W. Zhang*<sup>1</sup>, <sup>1</sup>*Huazhong Univ. of Sci. and Tech. (China)*



**14:45 J-4-04**

A Theoretical Investigation On MoS<sub>2</sub> Nanopore Power Generators

°Z. Huang<sup>1</sup>, M. Tsutsui<sup>2</sup>, Y. Zhang<sup>1</sup>, Y. H. He<sup>1</sup>, X. S. Miao<sup>1</sup>, M. Taniguchi<sup>2</sup>, <sup>1</sup>Huazhong Univ. of Sci. and Tech. (China), <sup>2</sup>Osaka Univ. (Japan)

**15:00 J-4-05 (Late News)**

Chemical Sensing using Graphene-based Surface-Acoustic-Wave Sensor

°S. Okuda<sup>1,2</sup>, T. Ono<sup>1</sup>, Y. Kanai<sup>1</sup>, M. Shimatani<sup>2</sup>, S. Ogawa<sup>2</sup>, T. Ikuta<sup>1,3</sup>, K. Inoue<sup>1</sup>, K. Maehashi<sup>1,3</sup>, K. Matsumoto<sup>1</sup>, <sup>1</sup>Osaka Univ. (Japan), <sup>2</sup>Mitsubishi Electric Corp. (Japan), <sup>3</sup>Tokyo Univ. of Agri. & Tech. (Japan)

**01: Advanced LSI Processing & Materials Science**

**K-3: Ge MOS**

**9:30-11:25 Meeting Room 8**

Session Chair: K. Yamamoto (Kyushu Univ.)

M. Kadoshima (Renesas Electronics Corp.)

**9:30 K-3-01**

A new kinetic model for thermal oxidation of Ge

°X. Wang<sup>1</sup>, T. Nishimura<sup>1</sup>, T. Yajima<sup>1</sup>, A. Toriumi<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan)

**9:50 K-3-02**

Ge Oxidation does not follow the Deal-Grove Mechanism

H. Li<sup>1</sup>, °J. Robertson<sup>1</sup>, <sup>1</sup>Cambridge Univ. (UK)

**10:10 K-3-03**

Impact of reaction kinetics at GeO<sub>2</sub>/Si for high-performance SiGe gate stacks

°W. Song<sup>1</sup>, A. Toriumi<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan)

**10:30 K-3-04**

Role of Y-doping into GeO<sub>2</sub> in Ge gate stack reliability

°X. Tang<sup>1,2</sup>, A. Toriumi<sup>1</sup>, <sup>1</sup>Univ. of Tokyo (Japan), <sup>2</sup>Nanjing Univ. (China)

Thursday, September 21

**10:50 K-3-05**

Ge and O Valence States in GeO<sub>x</sub> Interfacial Layer on Hole Mobility of Low EOT Ge pMOSFET

°J. -S. Li<sup>1</sup>, S. -H. Yi<sup>1</sup>, W. -Y. Hsu<sup>1</sup>, J. Huang<sup>1</sup>, C. -W. Hsu<sup>1</sup>, T. -Y. Wu<sup>1</sup>, D. -B. Ruan<sup>1</sup>, K. -S. Chang-Liao<sup>1</sup>, <sup>1</sup>National Tsing Hua Univ. (Taiwan)

**11:10 K-3-06 (Late News)**

Dependence of Channel Mobility on Substrate Impurity Concentration for Metal Source/Drain Ge MOSFETs

°T. Sakaguchi<sup>1</sup>, K. Akiyama<sup>1</sup>, K. Yamamoto<sup>1</sup>, D. Wang<sup>1</sup>, H. Nakashima<sup>1</sup>, <sup>1</sup>Kyushu Univ. (Japan)

**11:25-11:35 Coffee Break**

**Short Oral Presentation**

**Area 1:**

**PS-1**

**11:35-11:47 Meeting Room 8**

Session Chair: H. Itokawa (Toshiba Memory Corp.)

**11:47-14:00 Lunch**

**01: Advanced LSI Processing & Materials Science**

**K-4: Process Technology**

**14:00-15:30 Meeting Room 8**

Session Chair: L. Grenouillet (CEA-Leti)

G. Nakamura (Tokyo Electron Ltd.)

**14:00 K-4-01 (Invited)**

Ion implantation technology for advanced ULSI devices

°T. Kuroi<sup>1</sup>, <sup>1</sup>Nissin Ion Equipment Co., Ltd. (Japan)

**14:30 K-4-02**

CMOS Integration of Thermally Stable Diffusion and Gate Replacement (D&GR) High-k/Metal Gate Stacks in DRAM Periphery Transistors

°E. Dentoni Litta<sup>1</sup>, R. Ritzenthaler<sup>1</sup>, T. Schram<sup>1</sup>, A. Spessot<sup>1</sup>, B. O'Sullivan<sup>1</sup>, Y. Ji<sup>2</sup>, G. Mannaert<sup>1</sup>, C. Lorant<sup>1</sup>, F. Sebaai<sup>1</sup>, A. Thiam<sup>1</sup>, M. Ercken<sup>1</sup>, S. Demuynck<sup>1</sup>, N. Horiguchi<sup>1</sup>,

## Thursday, September 21

<sup>1</sup>IMEC (Belgium), <sup>2</sup>SK Hynix (Korea)

### 14:50 K-4-03

S/D Contact Solutions to Enable Contact Resistivity <1E-9 for 5nm and Beyond

°C. -Y. Chang<sup>1</sup>, F. A. Khaja<sup>1</sup>, K. E. Hollar<sup>1</sup>, K. V. Rao<sup>1</sup>, S. Munnangi<sup>1</sup>, Y. Chen<sup>1</sup>, M. Okazaki<sup>1</sup>, Y. -C. Huang<sup>1</sup>, X. Li<sup>1</sup>, H. Chung<sup>1</sup>, O. Chan<sup>1</sup>, C. Lazik<sup>1</sup>, M. Jin<sup>1</sup>, H. Zhou<sup>1</sup>, A. Mayur<sup>1</sup>, R. Hung<sup>1</sup>, N. Kim<sup>1</sup>, <sup>1</sup>Applied Materials, Inc (USA)

### 15:10 K-4-04

Hot-C<sup>+</sup>-Ion Implantation Optimization for Forming Nano-SiC Region at Surface (100)SOI Substrate

°T. Mizuno<sup>1</sup>, Y. Omata<sup>1</sup>, S. Nakada<sup>1</sup>, T. Aoki<sup>1</sup>, T. Sasaki<sup>2</sup>, <sup>1</sup>Kanagawa Univ. (Japan), <sup>2</sup>Toshiba Nanoanalysis Corp. (Japan)

## 08: Advanced Material Synthesis and Crystal Growth Technology

### M-3: Group IV Materials

#### 9:30-11:00 Meeting Room 2

Session Chair: T. Sadoh (Kyushu Univ.)

H. Tatsuoka (Shizuoka Univ.)

#### 9:30 M-3-01 (Invited)

Recent progress of crystal growth, conductivity control and solar cells of semiconducting barium disilicide

°T. Suemasu<sup>1</sup>, <sup>1</sup>Univ. of Tsukuba (Japan)

#### 10:00 M-3-02

Growth of 2D Crystal of Group-IV Elements on Epitaxial Ag (111)

°K. Ito<sup>1</sup>, A. Ohta<sup>1</sup>, M. Kurosawa<sup>1</sup>, M. Araidai<sup>1</sup>, M. Ikeda<sup>1</sup>, K. Makihara<sup>1</sup>, S. Miyazaki<sup>1</sup>, <sup>1</sup>Nagoya Univ. (Japan)

#### 10:15 M-3-03

Structural and Photoluminescence Properties of Si-based Nanosheet Bundles Rooted on Si Substrates

P. Yuan<sup>1</sup>, R. Tamaki<sup>2</sup>, S. Kusazaki<sup>1</sup>, N. Atsumi<sup>1</sup>, Y. Saito<sup>1</sup>, Y. Kumazawa<sup>1</sup>, N. Ahsan<sup>2</sup>, Y. Okada<sup>2</sup>, °H. Tatsuoka<sup>1</sup>,

**Thursday, September 21**

<sup>1</sup>Shizuoka Univ. (Japan), <sup>2</sup>Univ. of Tokyo (Japan)

**10:30 M-3-04**

SiC Nano-Dots in Bulk-Si Substrate Fabricated by Hot-C<sup>+</sup>-  
Ion Implantation Technique

<sup>o</sup>T. Mizuno<sup>1</sup>, S. Nakada<sup>1</sup>, M. Yamamoto<sup>1</sup>, S. Irie<sup>1</sup>, Y. Omata<sup>1</sup>,  
T. Aoki<sup>1</sup>, T. Sameshima<sup>2</sup>, <sup>1</sup>Kanagawa Univ. (Japan), <sup>2</sup>Tokyo  
Univ. of Agri. & Tech. (Japan)

**10:45 M-3-05**

Sb-doping effect on thermal and electrical properties of  
Ge-rich Ge<sub>1-x</sub>Sn<sub>x</sub> layers

<sup>o</sup>T. Iwahashi<sup>1</sup>, M. Kurosawa<sup>1,2,3</sup>, N. Uchida<sup>4</sup>, Y. Ohishi<sup>5</sup>, T.  
Maeda<sup>4</sup>, O. Nakatsuka<sup>1,6</sup>, S. Zaima<sup>6</sup>, <sup>1</sup>Grad. Sch. of Eng.,  
Nagoya Univ. (Japan), <sup>2</sup>IAR, Nagoya Univ. (Japan),  
<sup>3</sup>PRESTO-JST (Japan), <sup>4</sup>NERI-AIST (Japan), <sup>5</sup>Grad. Sch.  
of Eng., Osaka Univ. (Japan), <sup>6</sup>IMaSS, Nagoya Univ.  
(Japan)

**11:00-11:35 Coffee Break**

**Short Oral Presentation**

**Area 8:**

**PS-8**

**11:35-12:05 Meeting Room 2**

Session Chair: A. Kikuchi (Sophia Univ.)

T. Iwai (Fujitsu Labs. Ltd.)

**12:05-14:00 Lunch**

**Luncheon Seminar**

**12:45-13:45**

EAG Nano Science Corporation (Hagi Conference Room)

Springer Nature (Tachibana Conference Room)

**08: Advanced Material Synthesis and Crystal Growth  
Technology**

**M-4: Germanium based Semiconductors**

**14:00-15:15 Meeting Room 2**

Session Chair: H. Tatsuoka (Shizuoka Univ.)

A. Kikuchi (Sophia Univ.)

**14:00 M-4-01**

High Substitutional-Sn-Concentration GeSn-on-Insulator  
by Weak-Laser-Irradiation-Enhanced Solid-Phase  
Crystallization at Low-Temperature ( $\sim 170^\circ\text{C}$ )

$^\circ$ T. Sugino<sup>1</sup>, K. Moto<sup>1</sup>, R. Matsumura<sup>1</sup>, H. Ikenoue<sup>1</sup>, M.  
Miyao<sup>1</sup>, T. Sadoh<sup>1</sup>, <sup>1</sup>Kyushu Univ. (Japan)

**14:15 M-4-02**

Dopants behavior in polycrystallization of heavily doped  
Ge<sub>1-x</sub>Sn<sub>x</sub> layer using pulsed laser annealing in water

$^\circ$ K. Takahashi<sup>1,2</sup>, M. Kurosawa<sup>1,3</sup>, H. Ikenoue<sup>4</sup>, M.  
Sakashita<sup>1</sup>, O. Nakatsuka<sup>1</sup>, S. Zaima<sup>1</sup>, <sup>1</sup>Nagoya Univ.  
(Japan), <sup>2</sup>JSPS Res. Fellow (Japan), <sup>3</sup>PRESTO-JST  
(Japan), <sup>4</sup>Kyushu Univ. (Japan)

**14:30 M-4-03**

Grain Boundary Engineering of Solid-Phase Crystallized  
Ge on Glass by Controlling Atomic Density of Precursor

$^\circ$ R. Yoshimine<sup>1</sup>, K. Toko<sup>1</sup>, T. Suemasu<sup>1</sup>, <sup>1</sup>Univ. of Tsukuba  
(Japan)

**14:45 M-4-04**

Effects of Deposition Temperature of Amorphous  
Precursors on Solid-Phase Crystallized Si<sub>1-x</sub>Ge<sub>x</sub> Thin Films  
on an Insulator

$^\circ$ D. Takahara<sup>1</sup>, K. Toko<sup>1</sup>, R. Yoshimine<sup>1</sup>, T. Suemasu<sup>1</sup>, <sup>1</sup>Univ.  
of Tsukuba (Japan)

**15:00 M-4-05**

Deposition mechanism of thin Si and Ge films promoted  
by liquid-phase reduction under ballistic hot electron  
incidence

$^\circ$ R. Suda<sup>1</sup>, A. Kojima<sup>1</sup>, N. Mori<sup>2</sup>, J. Shirakashi<sup>1</sup>, N.  
Koshida<sup>1</sup>, <sup>1</sup>Tokyo Univ. of Agri. & Tech. (Japan), <sup>2</sup>Osaka  
Univ. (Japan)

**06: Compound Semiconductor Electron Devices & Related Technologies**

**N-3: GaN Device Technologies I**

**9:30-11:00 Meeting Room 3**

Session Chair: K. Tsuda (Toshiba Infrastructure Systems & Solutions Corp.)  
N. Shigekawa (Osaka City Univ.)

**9:30 N-3-01 (Invited)**

Monolithically Integrated GaN-on-Si Power Circuits

°R. Reiner<sup>1</sup>, P. Waltereit<sup>1</sup>, B. Weiss<sup>1</sup>, S. Moench<sup>2</sup>, R. Quay<sup>1</sup>,  
O. Ambacher<sup>3</sup>, <sup>1</sup>Fraunhofer IAF (Germany), <sup>2</sup>Univ. of  
Stuttgart (Germany), <sup>3</sup>Univ. of Freiburg (Germany)

**10:00 N-3-02**

Unpassivated AlGaIn/GaN HEMTs with Ideal Sub-  
threshold Swing (~60mV/decade) on Extremely High  
Quality Free-standing GaN Substrate

°X. Liu<sup>1</sup>, H. Gu<sup>1</sup>, K. Li<sup>1</sup>, J. He<sup>1</sup>, K. Lai<sup>1</sup>, D. Zhu<sup>1</sup>, Y. Lu<sup>1</sup>, W.  
He<sup>1</sup>, J. Fang<sup>2</sup>, J. Wang<sup>3</sup>, H. -C. Kuo<sup>4</sup>, Z. Liu<sup>5</sup>, W. Liu<sup>6</sup>, K.  
-W. Ang<sup>5</sup>, Y. Hao<sup>2</sup>, K. Xu<sup>3</sup>, J. -P. Ao<sup>1,2</sup>, <sup>1</sup>Shenzhen Univ  
(China), <sup>2</sup>Xidian Univ. (China), <sup>3</sup>SINANO, CAS (China),  
<sup>4</sup>National Chiao Tung Univ. (Taiwan), <sup>5</sup>National Univ. of  
Singapore (Singapore), <sup>6</sup>Fudan Univ. (China)

**10:15 N-3-03**

Impact of Crystal Orientation on Ohmic Contact Resistance  
of Enhancement-Mode pGaN Gate High Electron Mobility  
Transistors on 200 mm Si Substrates

°M. Van Hove<sup>1</sup>, <sup>1</sup>IMEC (Belgium)

**10:30 N-3-04**

Threshold voltages of Al<sub>2</sub>O<sub>3</sub>/AlGaIn/GaN and AlTiO/  
AlGaIn/GaN metal-insulator-semiconductor devices

°S. P. Le<sup>1</sup>, T. Ui<sup>1</sup>, D. D. Nguyen<sup>1</sup>, T. Suzuki<sup>1</sup>, <sup>1</sup>JAIST (Japan)

**10:45 N-3-05**

Drain-induced barrier lowering in normally-off AlGaIn-  
GaN MOSFETs with single- or double-recess overlapped  
gate

°T. Sato<sup>1</sup>, K. Uryu<sup>1</sup>, J. Okayasu<sup>1</sup>, M. Kimishima<sup>1</sup>, T. Suzuki<sup>2</sup>,  
<sup>1</sup>Advantest Labs. Ltd. (Japan), <sup>2</sup>JAIST (Japan)

Thursday, September 21

11:00-11:35 Coffee Break

Short Oral Presentation

Area 6:

PS-6

11:35-12:03 Meeting Room 3

Session Chair: T. Suzuki (JAIST)

K. Tsuda (Toshiba Infrastructure Systems & Solutions Corp.)

12:03-14:00 Lunch

Luncheon Seminar

12:45-13:45

EAG Nano Science Corporation (Hagi Conference Room)

Springer Nature (Tachibana Conference Room)

06: Compound Semiconductor Electron Devices & Related Technologies

N-4: GaN Device Technologies II

14:00-15:15 Meeting Room 3

Session Chair: S. Suzuki (Tokyo Tech)

S. Ozaki (Fujitsu Labs. Ltd.)

14:00 N-4-01 (Invited)

High Frequency GaN HEMTs for RF MMIC Applications

*M. Micovic<sup>1</sup>, °D. F. Brown<sup>1</sup>, D. Regan<sup>1</sup>, J. Wong<sup>1</sup>, Y. Tang<sup>1</sup>,  
F. Herrault<sup>1</sup>, D. Santos<sup>1</sup>, S. D. Burnham<sup>1</sup>, J. Tai<sup>1</sup>, E.  
Prophet<sup>1</sup>, I. Khalaf<sup>1</sup>, C. McGuire<sup>1</sup>, H. Bracamontes<sup>1</sup>, H.  
Fung<sup>1</sup>, A. Schmitz<sup>1</sup>, <sup>1</sup>HRL Labs. (USA)*

14:30 N-4-02

High Performance Tri-Gate AlGaIn/GaN Power HEMTs

*°J. H. Lee<sup>1</sup>, C. C. Hsu<sup>1</sup>, Y. C. Lin<sup>1</sup>, J. N. Yao<sup>1</sup>, C. Y. Wu<sup>1</sup>, E.  
Y. Chang<sup>1</sup>, <sup>1</sup>National Chiao Tung Univ. (Taiwan)*

14:45 N-4-03

Back-gate effect on p-channel GaN MOSFETs on  
Polarization-Junction Substrate

*°T. Hoshii<sup>1</sup>, R. Takayama<sup>1</sup>, A. Nakajima<sup>2</sup>, S. Nishizawa<sup>3</sup>, H.  
Ohashi<sup>1</sup>, K. Kakushima<sup>1</sup>, H. Wakabayashi<sup>1</sup>, K. Tsutsui<sup>1</sup>,*

**Thursday, September 21**

<sup>1</sup>Tokyo Tech (Japan), <sup>2</sup>AIST (Japan), <sup>3</sup>Kyushu Univ. (Japan)

**15:00 N-4-04 (Late News)**

MOVPE Growth Behavior of AlGa<sub>N</sub>/Ga<sub>N</sub>

Heterostructures with AlGa<sub>N</sub> Directly on RIE-Ga<sub>N</sub>

Showing a High Electron Mobility (>1300 cm<sup>2</sup>/Vs)

°A. Yamamoto<sup>1</sup>, K. Kanatani<sup>1</sup>, S. Makino<sup>1</sup>, M. Kuzuhara<sup>1</sup>,

<sup>1</sup>Univ. of Fukui (Japan)

<b>14: Power Devices and Materials</b>
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**O-3: Ga<sub>2</sub>O<sub>3</sub> and Diamond Power Devices**

**9:30-11:00 Meeting Room 4**

Session Chair: T. Makino (AIST)

D. Hisamoto (Hitachi, Ltd.)

**9:30 O-3-01 (Invited)**

Characterization of Ga<sub>2</sub>O<sub>3</sub> MOSFETs for Low to Medium Power Applications

°G. H. Jessen<sup>1</sup>, K. Chabak<sup>1</sup>, A. Green<sup>2,1</sup>, N. Moser<sup>3,1</sup>, J.

McCandless<sup>2,1</sup>, K. Leedy<sup>1</sup>, A. Crespo<sup>1</sup>, S. Tetlak<sup>1</sup>, <sup>1</sup>Air Force

Research Lab. (USA), <sup>2</sup>KBRwyle (USA), <sup>3</sup>George Mason

Univ. (USA)

**10:00 O-3-02 (Invited)**

Normally Off Diamond Metal-Oxide-Semiconductor Field-Effect-Transistor with Inversion Mode

°T. Matsumoto<sup>1,2</sup>, H. Kato<sup>2</sup>, T. Makino<sup>2</sup>, M. Ogura<sup>2</sup>, D.

Takeuchi<sup>2</sup>, T. Inokuma<sup>1</sup>, N. Tokuda<sup>1,2</sup>, S. Yamasaki<sup>2</sup>,

<sup>1</sup>Kanazawa Univ. (Japan), <sup>2</sup>AIST (Japan)

**10:30 O-3-03**

Threshold control of diamond MESFET by MWCVD growth conditions

°H. Kawashima<sup>1</sup>, H. Umezawa<sup>1</sup>, S. Ohmagari<sup>1</sup>, R. Tamano<sup>2</sup>,

T. Saito<sup>2</sup>, Y. Mokuno<sup>1</sup>, <sup>1</sup>AIST (Japan), <sup>2</sup>Osaka Pref. Univ.

(Japan)

**10:45 O-3-04**

Normally-off Diamond p-FET Application in Cascode with



**Thursday, September 21**

Breakdown Voltage over 1.7 kv

<sup>o</sup>*T. Bi<sup>1</sup>, J. Niu<sup>1</sup>, N. Oi<sup>1</sup>, M. Inaba<sup>1</sup>, T. Sasaki<sup>1</sup>, K. Hiroshi<sup>1</sup>,*  
*<sup>1</sup>Waseda Univ. (Japan)*

**11:00-11:35 Coffee Break**

**Short Oral Presentation**

**Area 14:**

**PS-14**

**11:35-11:57 Meeting Room 4**

Session Chair: H. Fujiwara (Toyota Motor Corp.)  
T. Makino (AIST)

**11:57-14:00 Lunch**

**Luncheon Seminar**

**12:45-13:45**

EAG Nano Science Corporation (Hagi Conference Room)  
Springer Nature (Tachibana Conference Room)

**14: Power Devices and Materials**

**O-4: Silicon Power Devices and Related Technologies**

**14:00-15:00 Meeting Room 4**

Session Chair: S. Matsumoto (Kyushu Inst. of Tech.)  
D. Hisamoto (Hitachi, Ltd.)

**14:00 O-4-01**

Current conduction in H<sub>2</sub>O-grown ALD-Al<sub>2</sub>O<sub>3</sub> films on Si substrates

<sup>o</sup>*S. Okubo<sup>1</sup>, D. Matsumura<sup>1</sup>, K. Horikawa<sup>1</sup>, A. Hiraiwa<sup>1,2</sup>,*  
*H. Kawarada<sup>1</sup>, <sup>1</sup>Waseda Univ. (Japan), <sup>2</sup>Nagoya Univ. (Japan)*

**14:15 O-4-02**

Structure Based Compact Model for Output Capacitance of Trench Field-Plate MOSFET to Enable Power Loss Prediction

<sup>o</sup>*K. Kobayashi<sup>1</sup>, M. Sudo<sup>1</sup>, I. Omura<sup>1</sup>, <sup>1</sup>Kyushu Inst. of Tech. (Japan)*

**Thursday, September 21**

**14:30 O-4-03**

A Novel Edge Termination Design for Superjunction  
VDMOS

*°C. -H. Cheng<sup>1</sup>, C. -F. Huang<sup>1</sup>, K. -Y. Lee<sup>2</sup>, <sup>1</sup>National Tsing  
Hua Univ. (Taiwan), <sup>2</sup>National Taiwan Univ. (Taiwan)*

**14:45 O-4-04**

Temperature Distribution Imaging inside Power Devices  
by Real-Time Simulation

*°A. Watanabe<sup>1</sup>, R. Nagao<sup>1</sup>, I. Omura<sup>1</sup>, <sup>1</sup>Kyushu Inst. of  
Tech. (Japan)*